



## Material Content Data Sheet



<b>Sales Product Name</b>		TLE9201SG		<b>Issued</b>		9. January 2019		
<b>MA#</b>		MA001278434						
<b>Package</b>		PG-DSO-12-17		<b>Weight*</b>		375.41 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.352	1.43	1.43	14256	14256
leadframe	inorganic material	phosphorus	7723-14-0	0.061	0.02		162	
	non noble metal	iron	7439-89-6	0.202	0.05		538	
	non noble metal	copper	7440-50-8	201.897	53.78	53.85	537804	538504
	non noble metal	copper	7440-50-8	1.487	0.40	0.40	3960	3960
wire	non noble metal	copper	7440-50-8	1.487	0.40	0.40	3960	3960
encapsulation	organic material	carbon black	1333-86-4	0.310	0.08		826	
	plastics	epoxy resin	-	14.261	3.80		37988	
	inorganic material	silicondioxide	60676-86-0	140.442	37.41	41.29	374102	412916
leadfinish	non noble metal	tin	7440-31-5	3.243	0.86	0.86	8639	8639
plating	noble metal	silver	7440-22-4	2.024	0.54	0.54	5392	5392
solder	non noble metal	tin	7440-31-5	0.123	0.03		327	
	noble metal	silver	7440-22-4	0.153	0.04		408	
	non noble metal	lead	7439-92-1	5.856	1.56	1.63	15598	16333
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com